IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1					Form Type ³ Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information					
Supplie	r Information															
Company	name*	Company un	Company unique ID			Unique ID Authority					Response Date*					
onsemi													2025-05-24			
Contact N	lame		Title - Contact]	Phone - Contact*					Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Authorize	ed Representative*		Title - Representative]	Phone - Representative*				Email - Representative*					
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Da	ve Date Version Manufacturing Si		ring Site	Weight*		UOM	Unit Type		
		MOC3042VM 6		6PW ZC TRIAC DIP VDE			2025-05-24		1	LITEONFG		4	45.072	mg	Each	
Manufa	cturing Proccess Informat	ion					'	, , , , , , , , , , , , , , , , , , ,						1	1	
	Terminal Plating / Grid Array Material T		Cerminal Base Alloy J-STD-020 M		-STD-020 MSL	Rating	Peak Process Body Tempera		Body Temperatu	ture Max Time at Peak Tempe		Temperat	ure Num	nber of Reflow Cyc	eles	
	Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30 seco		secon	ds 3					
Comments	3															
or more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	0.4	mg	Supplier	Dimethyl Cyclosiloxanes	69430-24-6		0.04	mg
			Supplier	Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3		0.36	mg
Die	0.37	mg	Supplier	Silicon (Si)	7440-21-3		0.37	mg
Die Attach	0.3	mg	Supplier	Silver (Ag)	7440-22-4		0.246	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.054	mg
Die GaAs	0.11	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.11	mg
Lead Frame	108.322	mg	Supplier	Silver (Ag)	7440-22-4		0.68	mg
			Supplier	Zinc (Zn)	7440-66-6		0.13	mg
			Supplier	Iron (Fe)	7439-89-6		2.48	mg
			Supplier	Copper (Cu)	7440-50-8		105	mg
			Supplier	Phosphorus (P)	7723-14-0		0.032	mg
Mold Compound-White	327.22	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		81.805	mg
			В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		9.8166	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		44.1747	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		9.8166	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		163.61	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		17.9971	mg
Plating	6.7	mg	Supplier	Tin (Sn)	7440-31-5		6.7	mg
Wire Bond - Au	1.65	mg	Supplier	Gold (Au)	7440-57-5		1.65	mg